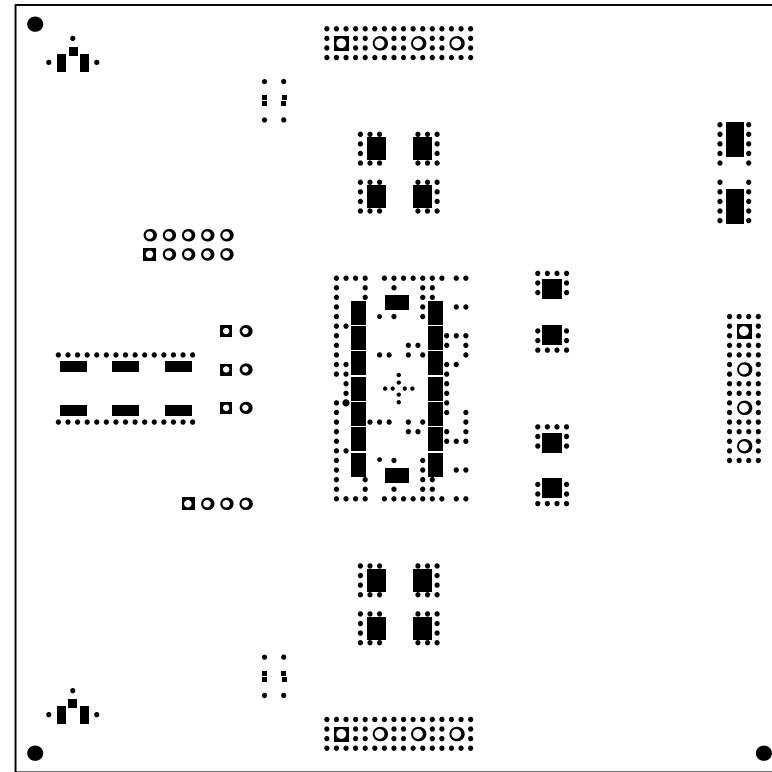
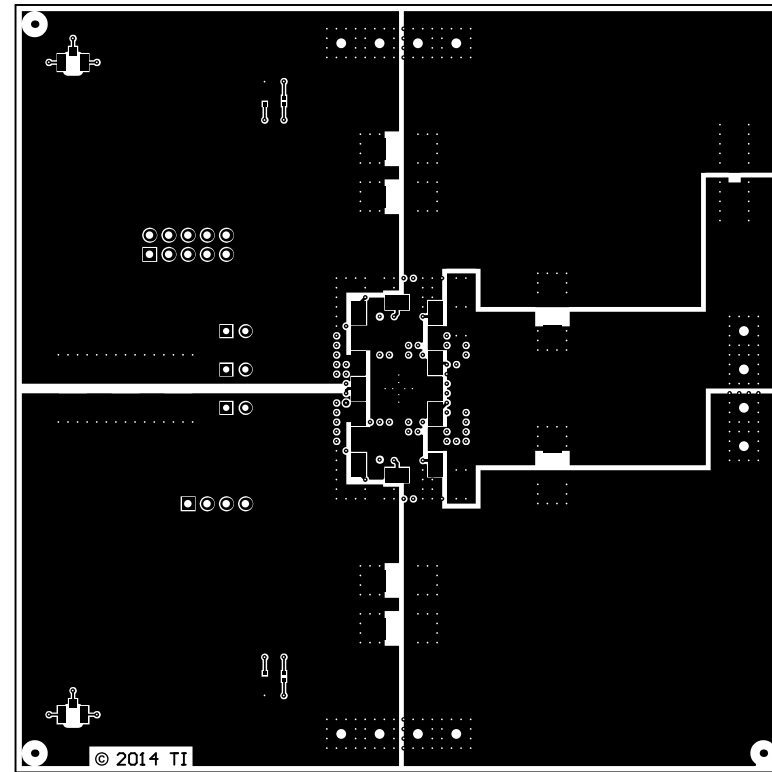


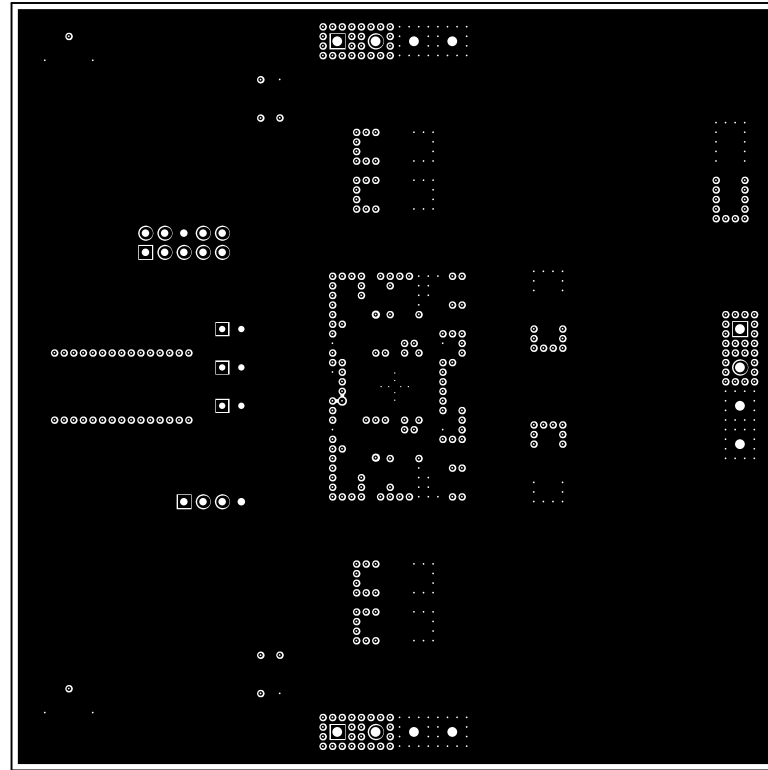
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8342	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 12/18/2014 9:50:14 PM	TEXAS INSTRUMENTS	



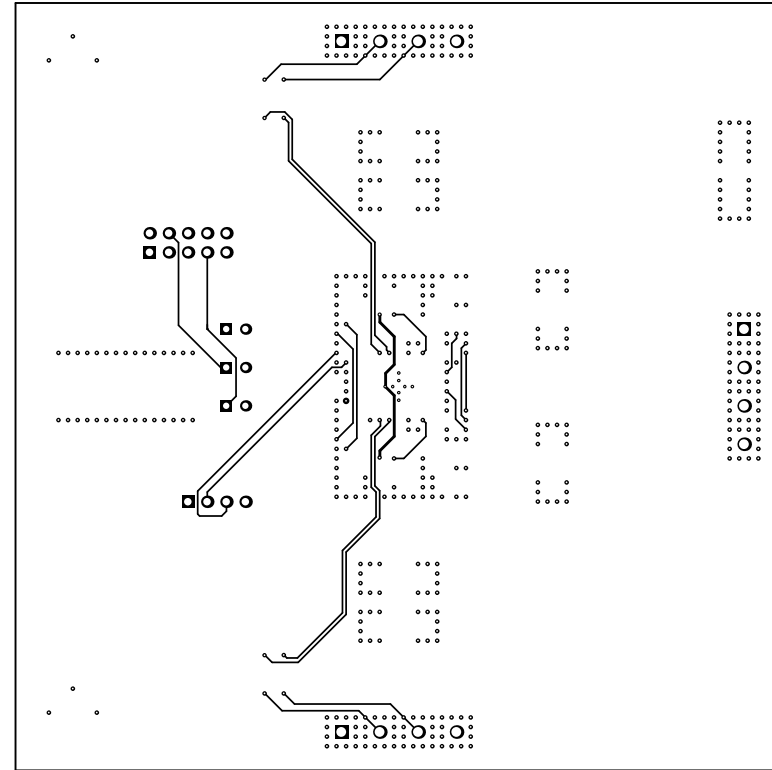
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8342	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 12/18/2014 9:50:16 PM	TEXAS INSTRUMENTS	



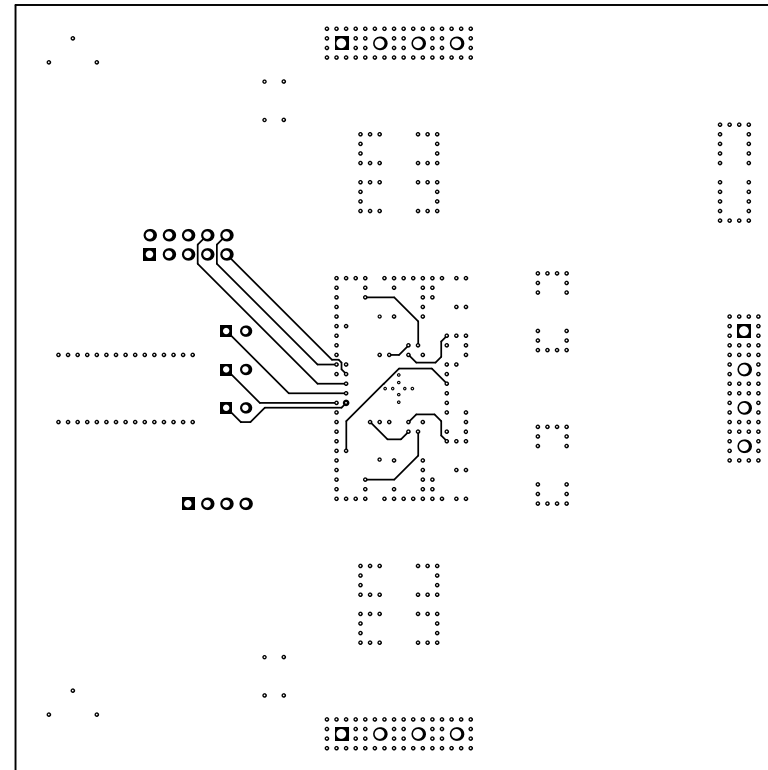
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8342	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 12/18/2014 9:50:18 PM	TEXAS INSTRUMENTS	



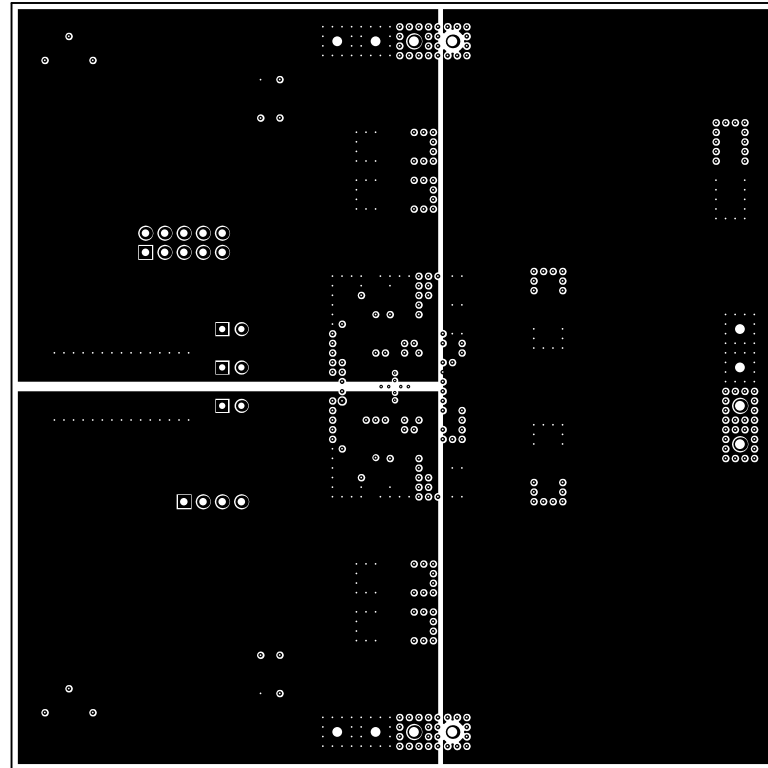
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8342	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer1	GENERATED : 12/18/2014 9:50:19 PM	TEXAS INSTRUMENTS	



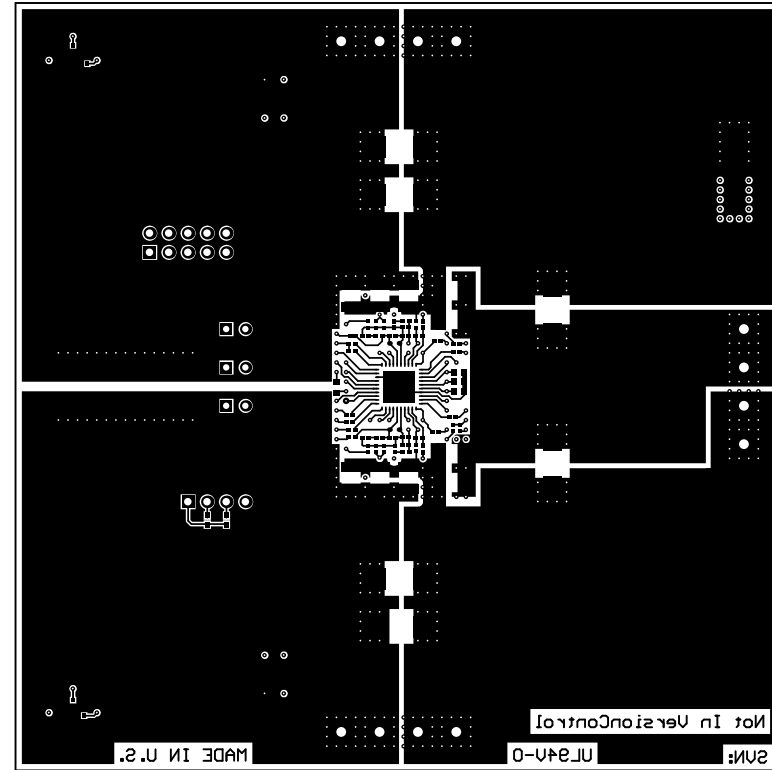
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8342	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer2	GENERATED : 12/18/2014 9:50:21 PM	TEXAS INSTRUMENTS	



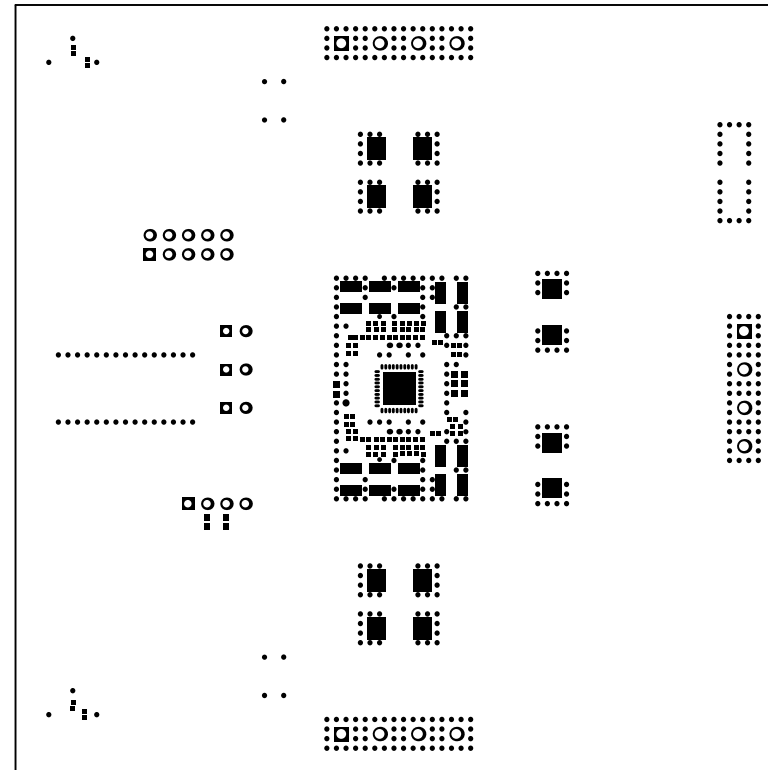
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8342	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer3	GENERATED : 12/18/2014 9:50:23 PM	TEXAS INSTRUMENTS	



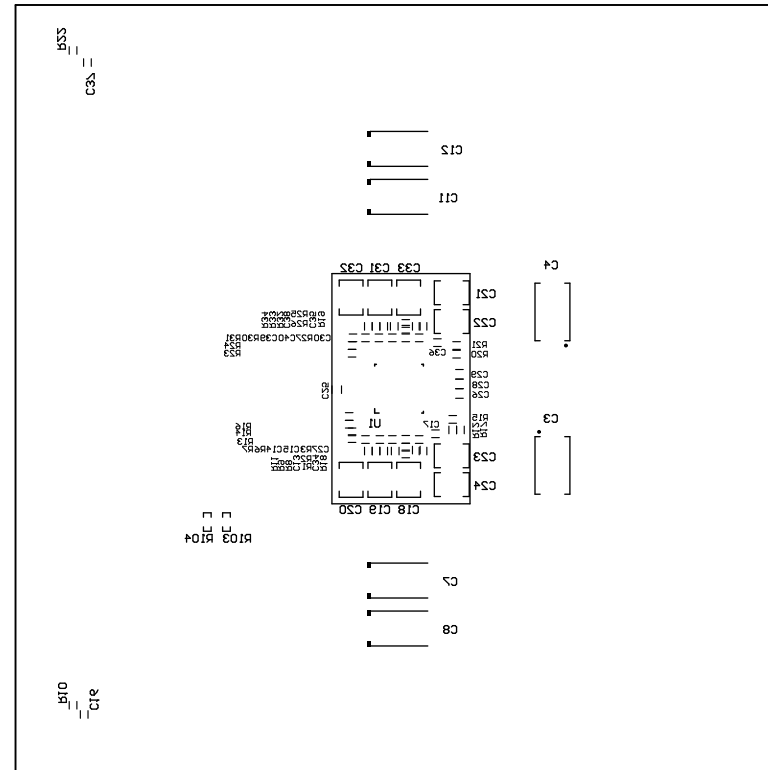
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8342	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer 4	GENERATED : 12/18/2014 9:50:25 PM	TEXAS INSTRUMENTS	



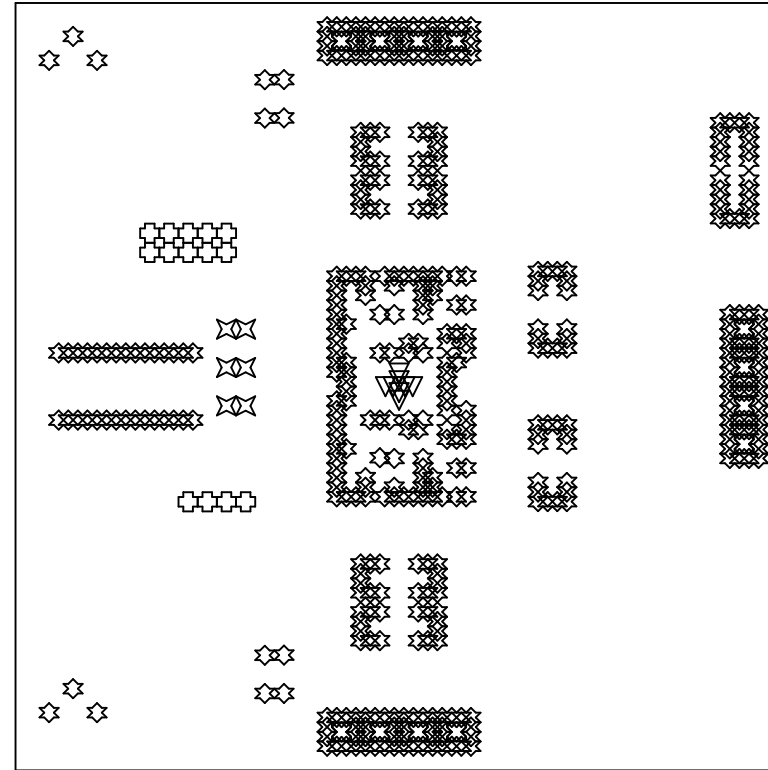
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8342	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 12/18/2014 9:50:26 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8342	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 12/18/2014 9:50:28 PM	TEXAS INSTRUMENTS	

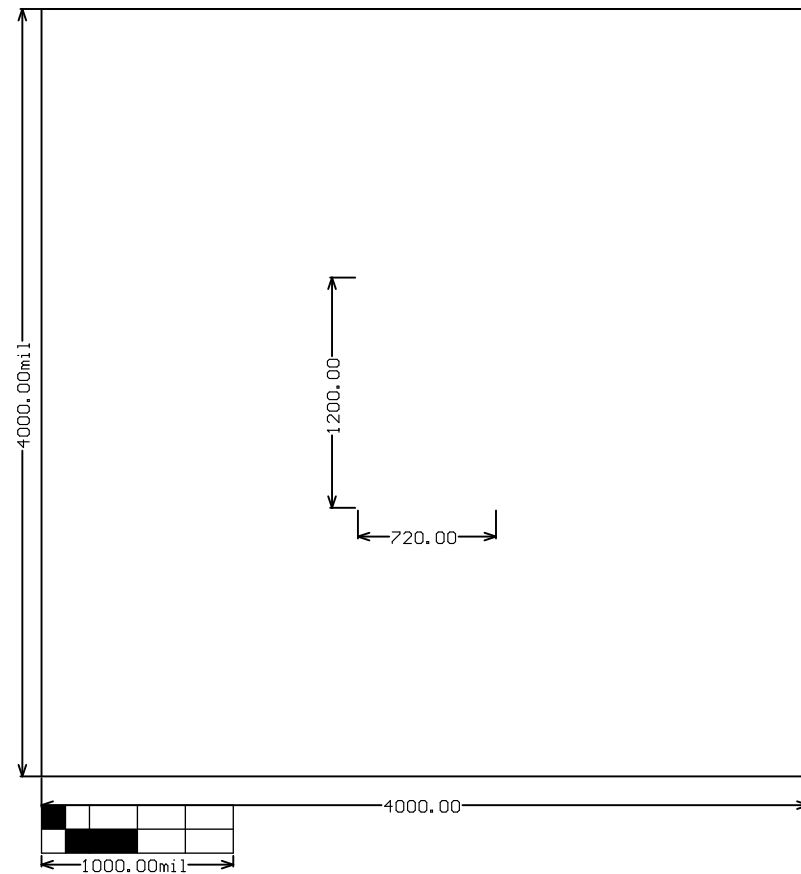


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8342	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 12/18/2014 9:50:30 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
▽	8	7.87mil (0.200mm)	PTH	Round
☆	420	10.00mil (0.254mm)	PTH	Round
⊗	6	33.46mil (0.850mm)	PTH	Round
⊙	14	40.00mil (1.016mm)	PTH	Round
⊗	12	51.18mil (1.300mm)	PTH	Round
	460 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8342	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 12/18/2014 9:50:31 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP8342	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 12/18/2014 9:50:33 PM	TEXAS INSTRUMENTS	

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